



## PC20x and PC302 NAND interfacing Applications Note 42.

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## 1 Introduction.

The purpose of this document is to introduce NAND flash memory technology, describing the hardware and software requirements when interfacing to NAND Flash to the PC202 and PC302 family of WCDMA Base band processors.

### 1.1 Basic NAND operation.

The NAND Flash array is organized in a series of blocks which are divided in several pages. This is shown in Section 3. Data is stored either in byte (8 bits) or half-word (16 bits) format depending on the device type. Each page is constituted of a main storage area and a spare area (physically similar) typically used for data error identification and correction, wear leveling etc...

One native property of NAND Flash devices is that they may contain a percentage of invalid blocks in the memory array. Before delivering the chip, these blocks are identified and marked as "Invalid Blocks" in the first or second page of each block. The existence of bad blocks does not affect the good memory blocks because each block is independent and individually isolated from the bit lines by block select transistors.

Because NAND Flash devices have a finite lifetime (approximately 100 000 write/erase cycles), additional invalid blocks may develop while being used. Storing data requires bad-block management and data error identification and correction. Refer to Section 2. picoChip PC20x and PC302 devices do not have native hardware support for these requirements so the user is required to implement these within software.

NAND Flash operations are fully controlled through a multiplexed I/O interface and additional control signals. Commands, addresses and data are transferred through the external input/output data bus (8-bit) to the dedicated internal registers. For 16-bit devices used with the PC20x, commands, addresses and data use the lower 8 bits (7 - 0), the upper 8 bits are only used during data-transfer cycles.

Read and program operations are performed on a per page basis whereas erase operations are performed on a block basis. To read or write from NAND Flash, a command sequence is issued to select a block and a page. After this selection, the entire page can be read or written. The command sequence normally consists of a Command Latch Cycle, an Address Latch Cycle and a Data Cycle — either read or write.

The waveforms shown in Figure 1 depict the successive accesses: Command Latch, Address Latch and Data Output. Notice that no command can be sent to the NAND Flash during tR due to its busy-state period.

### 1.2 PC20x and PC302 External Bus interface (EBI)

The PC20x and PC302 processor family features the external bus interface (EBI) to enable the interfacing to external Flash devices via integrated logic circuitry. The EBI provides Native support for NOR flash devices.

When interfacing to NAND flash technology there need to be additional software and control signals generated by the ARM board support package typically driving GPIO signals. In addition to the Invalid Block Definition, Identification and Error Checking and Correction required by all NAND type Flash devices with greater than 2% invalid Blocks.

## 2 Invalid Block Management and Error Corrected Code

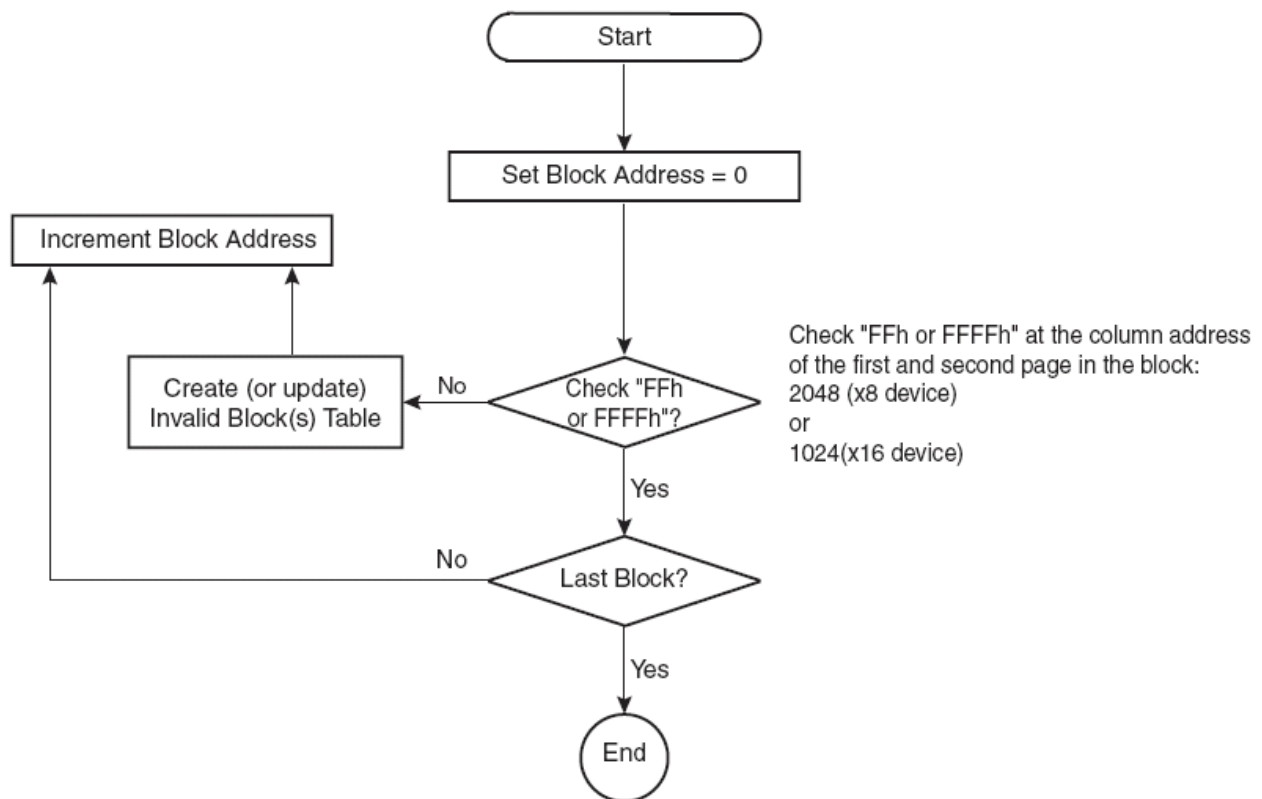
### 2.1 Invalid Block Definition

NAND flash devices contain a certain percentage of invalid blocks at the end of the production process. Invalid blocks are defined as blocks that contain one or more invalid bits.

### 2.2 Invalid Block Identification

Before shipping, every NAND flash device is tested with specific test patterns under different voltage and temperature conditions in order to identify memory locations containing errors. When errors are detected, the block to which the invalid memory location belongs is marked as an "Invalid Block". All device locations are erased (FFh for 8-bit devices, FFFFh for 16-bit devices) except locations where the invalid block information is written. The invalid block status is defined by the first byte (8-bit devices) or first half word (16-bit devices) in the spare area. Manufacturers make sure that either the first or second page of every invalid block has non-FFh (8-bit devices) or non-FFFFh (16-bit devices) data at the column address of 2048 (8-bit devices) or 1024 (16-bit devices). Since invalid block information (located in the spare area) written by the manufacturer is not write/erase protected, it can be lost and will be almost impossible to recover. In order to prevent losing this information, it is highly recommended to proceed to a block status mapping before any write or erase operation. Figure 1 Shows how bad block identification can be done by software.

**Figure 1: Bad Block Identification Flow Chart.**



## 2.3 Error Checking and Correction

NAND devices are subject to data failures that occur during device operation. To ensure data read/write integrity, system error checking and correction (ECC) algorithms should be implemented. picoChip's Family of Processors do not provide ECC hardware support. ECC is to be implemented by the end user within there application code.

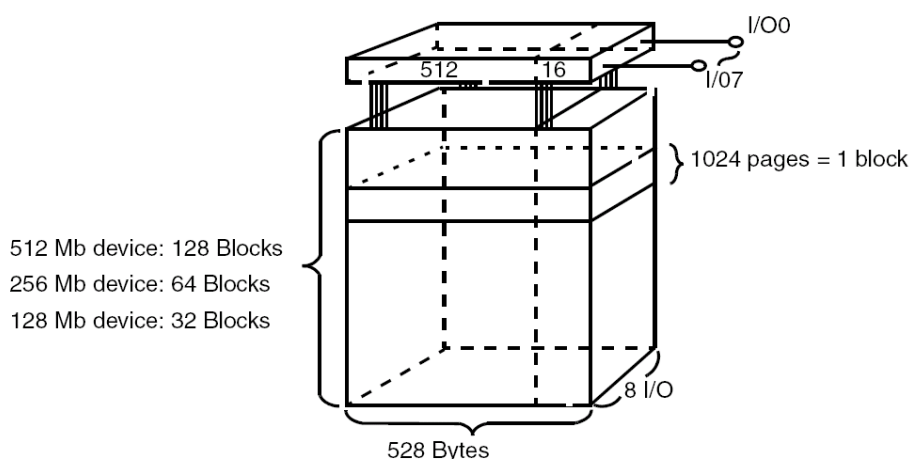
Micron ECC.c Example Code is attached for reference below.

## 3 NAND Flash Array Architecture

### 3.1 NAND Flash Example

The Spansion s30ML-p ORNAND™ Flash Family is used as an example however the implementation can be paired with any standard NAND flash devices that meet the timing specifications detailed within this application note. Figure 2 and Figure 3 show how the Spansion memory Arrays are organized for 8 bit and 16 bit devices respectively, Program operations work on page units whilst Erase operations are performed on block unites.

**Figure 2: NAND x8 Array Organisation**



#### X8 Array, Page and Block Description.

A page is made up of 528 Bytes in which 512 Bytes are used for main memory storage and 16 Bytes are reserved for redundancy or other usage. Various memory sizes are made up of a greater number of Block sizes.

1 Page = 528 Bytes

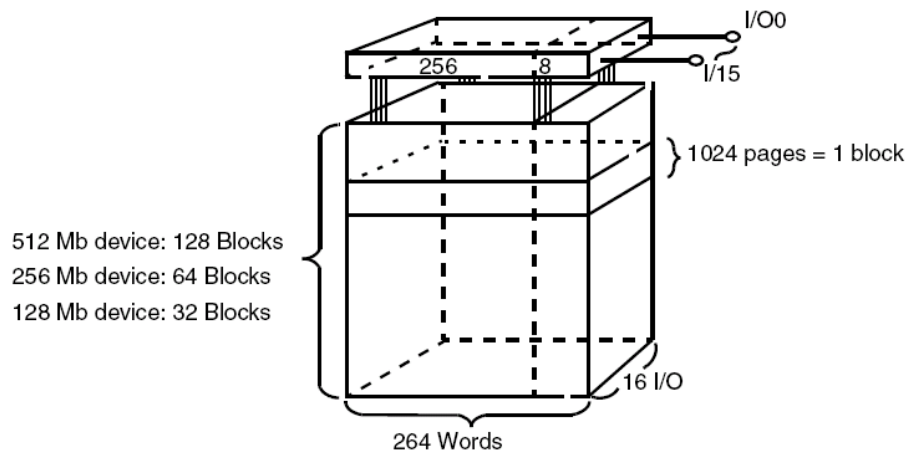
1 Block = 528 x 1024 Pages

**128Mb** memory – 528 Bytes x 1024 Pages x32 Blocks

**256Mb** memory – 528 Bytes x 1024 Pages x62 Blocks

**512Mb** memory – 528 Bytes x 1024 Pages x128 Blocks

**Figure 3: NAND x16 Array Organisation**



### X16 Array, Page and Block Description.

A page is made of 264 Words in which 256 Words are used for memory storage and 8 Words are reserved for redundancy or other usage.

1 Page = 264 Words

1 Block = 264 x 1024 Pages

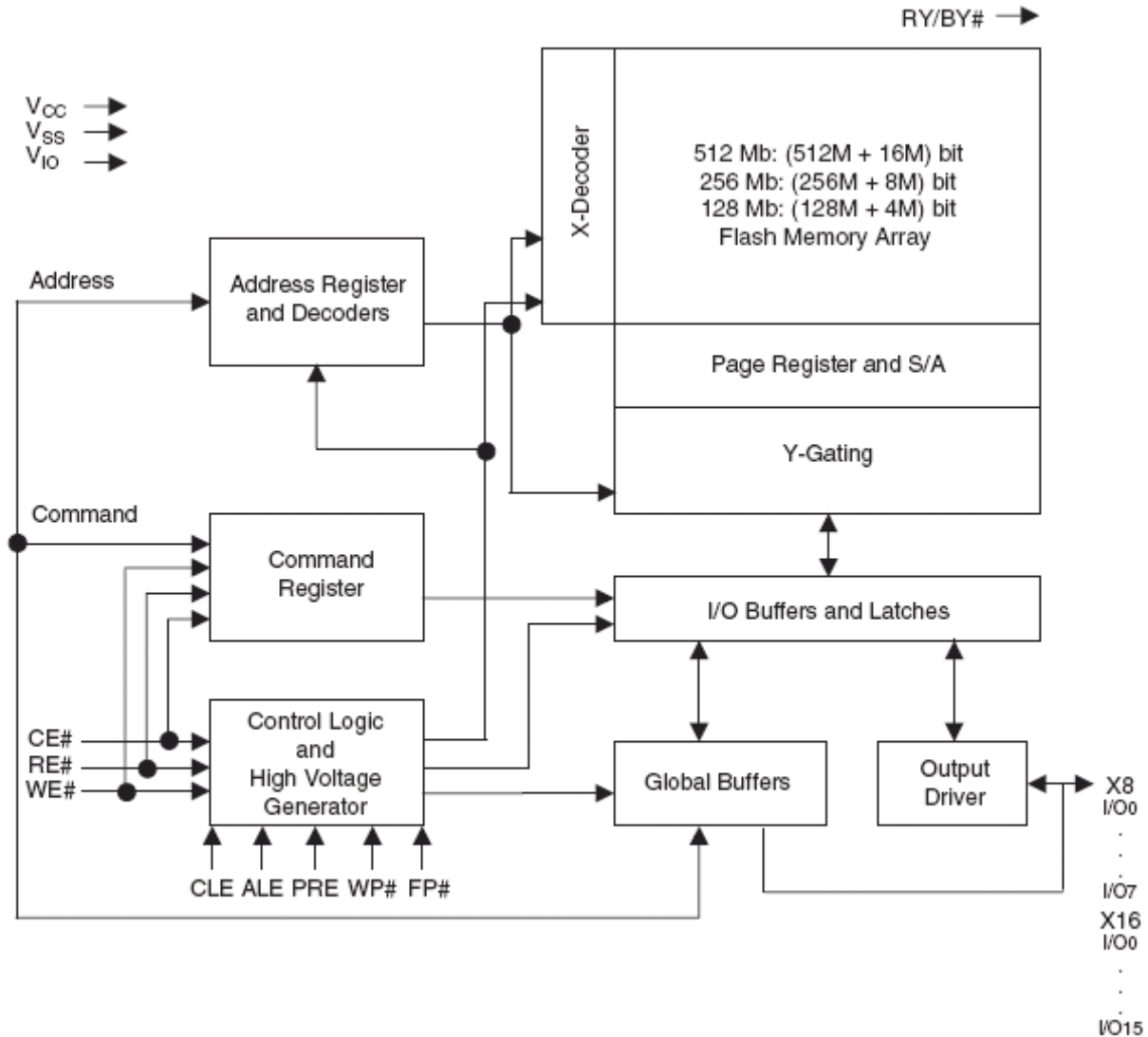
**128Mb** memory – 264 Words x 1024 Pages x32 Blocks

**256Mb** memory – 264 Words x 1024 Pages x62 Blocks

**512Mb** memory – 264 Words x 1024 Pages x128 Blocks

### 3.2 Spansion NAND Flash Block Diagram.

Figure 4: S30ML-P ORNAND™ Flash Family Block Diagram.



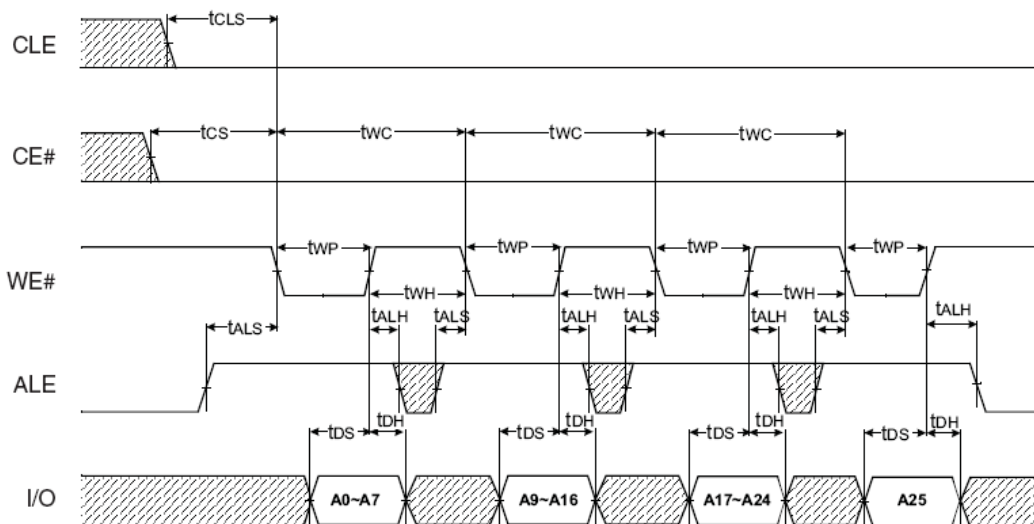
## 4 Comparison of NAND / EBI operations

### 4.1 NAND Operation

NAND Devices support various functions, all of the various operations are made up of three types of access these are the following A) Command Latch cycle, address Latch cycle and data in/out latch operation. Below details the various NAND access type that make up the various operations. (page read, block erase, status read... etc)

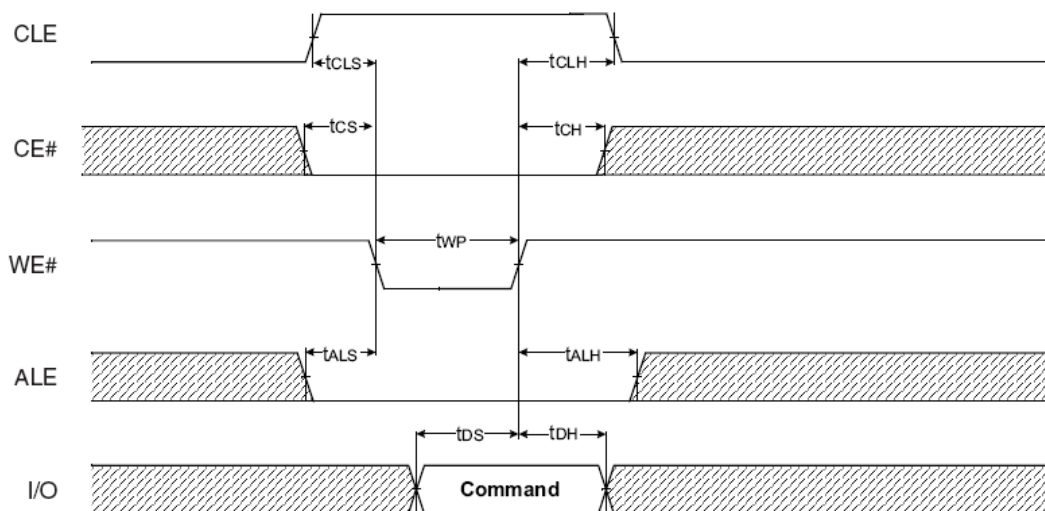
#### 4.1.1 NAND Address Latch Cycle.

Figure 5: Address Latch Cycle.



#### 4.1.2 NAND Command Latch Cycle.

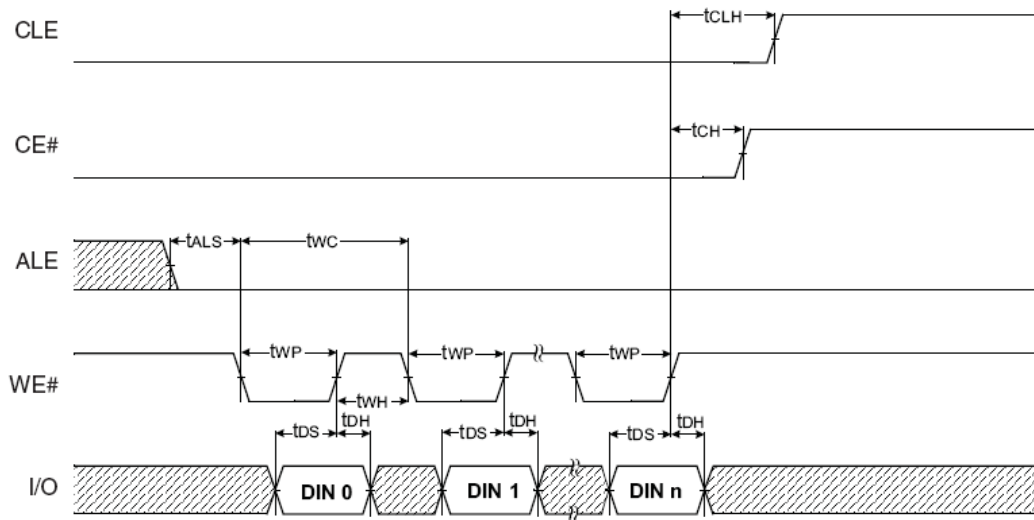
Figure 6: Command Latch Cycle.





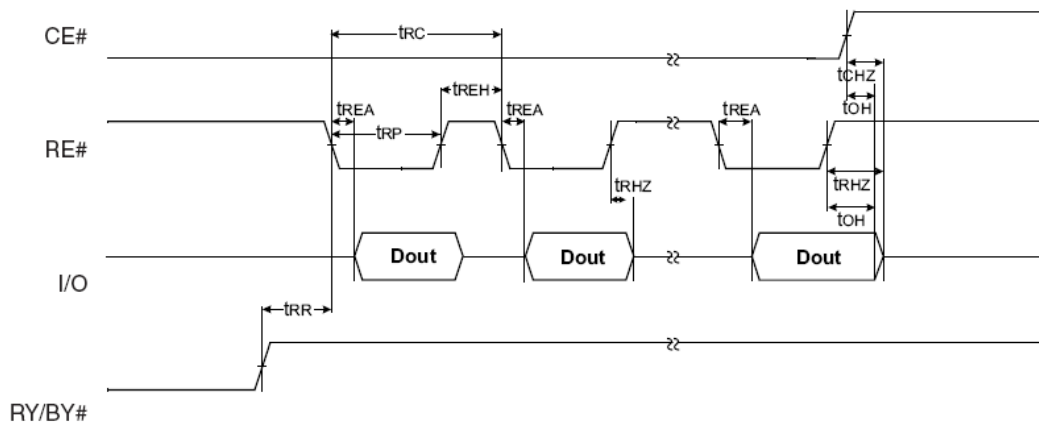
#### 4.1.3 NAND Data input latch operation.

Figure 7: Sequential data in Timing Diagram



#### 4.1.4 NAND Sequential Data out cycle

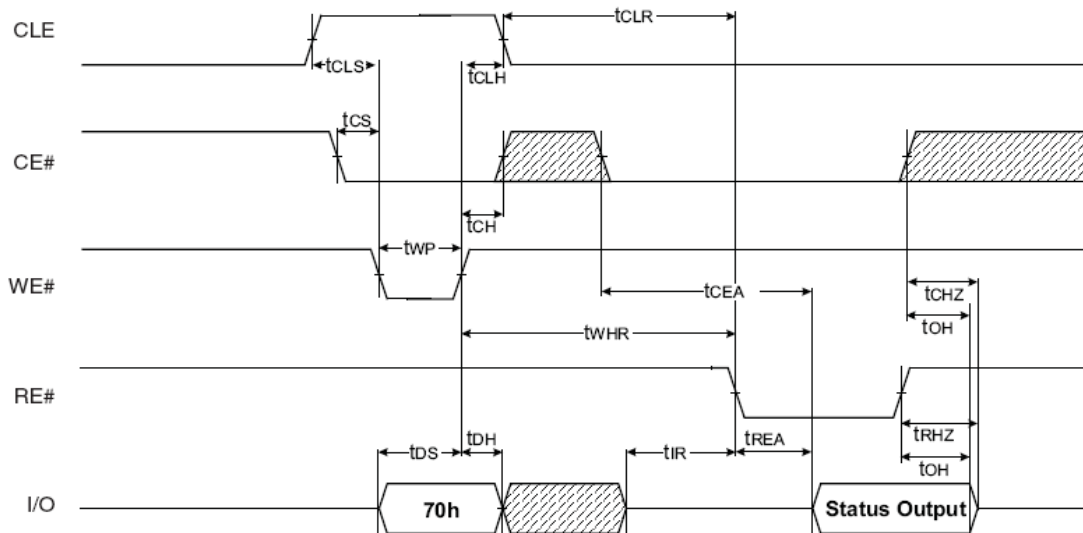
Figure 8: Sequential data out Timing Diagram



## 4.2 NAND operations

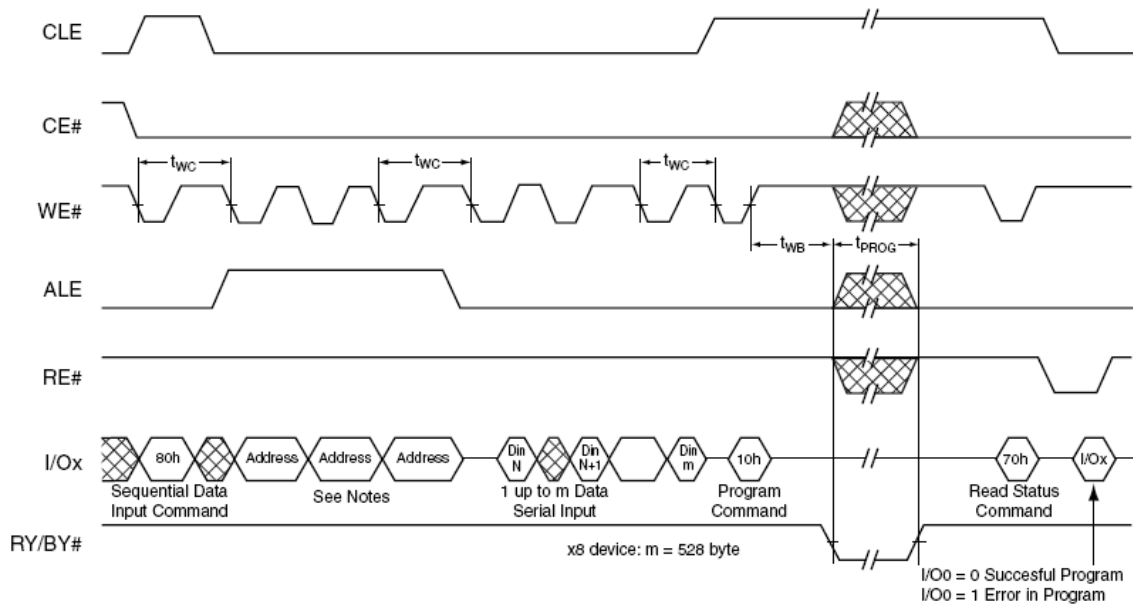
### 4.2.1 NAND Status Read Operation.

**Figure 9: Status Read Operation Timing Diagram**



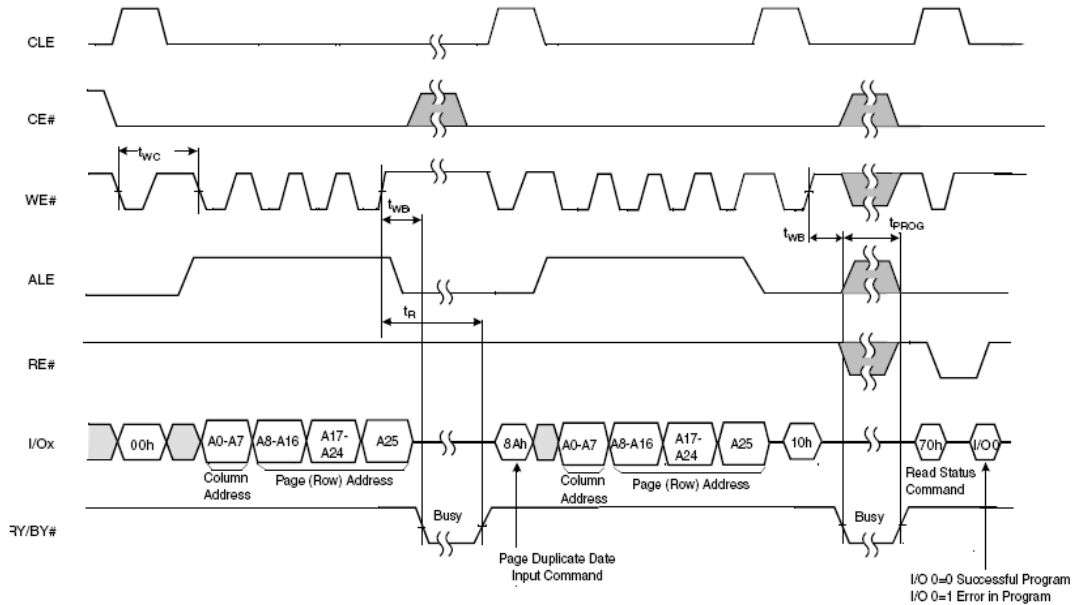
### 4.2.2 NAND Page Program Operation

**Figure 10: Page Program operation.**



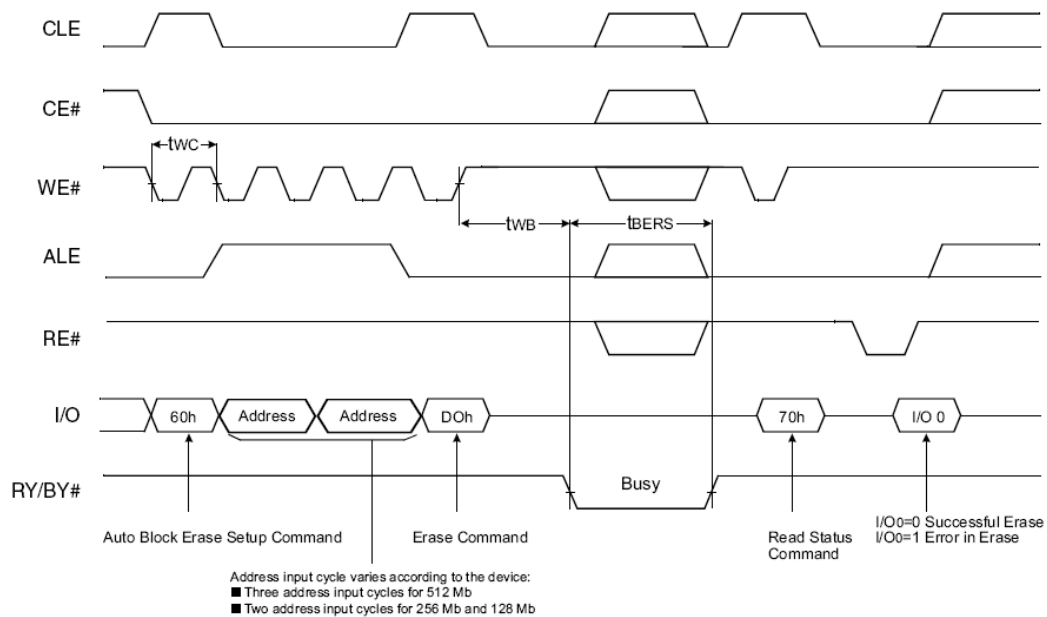
### 4.2.3 NAND Page Duplicate Program operation.

**Figure 11: Page duplicate program operation Timing Diagram**



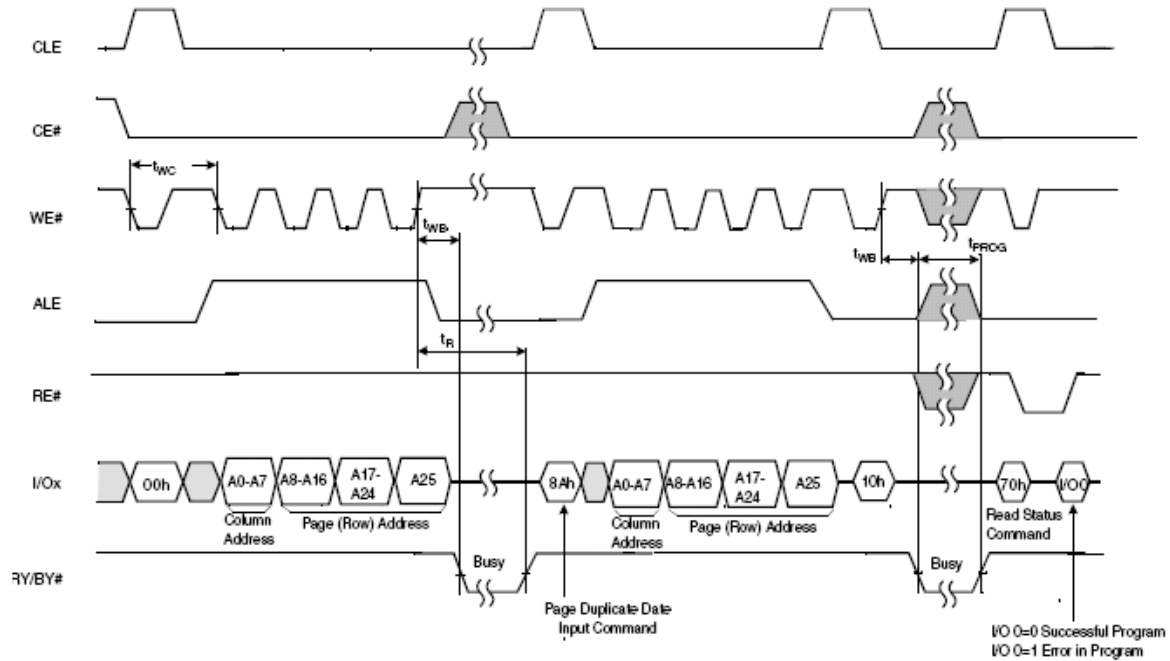
### 4.2.4 NAND Block Erase Operation Timing Diagram

**Figure 12: Block Erase operation Timing Diagram**



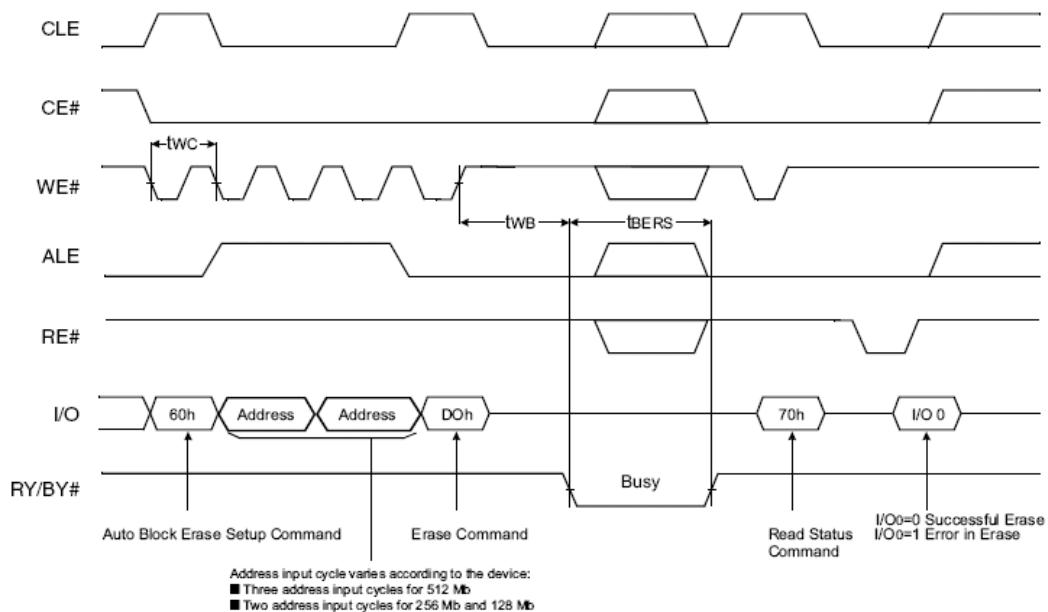
#### 4.2.5 NAND Page Program

**Figure 13: Page Program Operation Timing Diagram**



#### 4.2.6 NAND Block Erase Timing Diagram

**Figure 14: Block Erase Operation Timing Diagram**



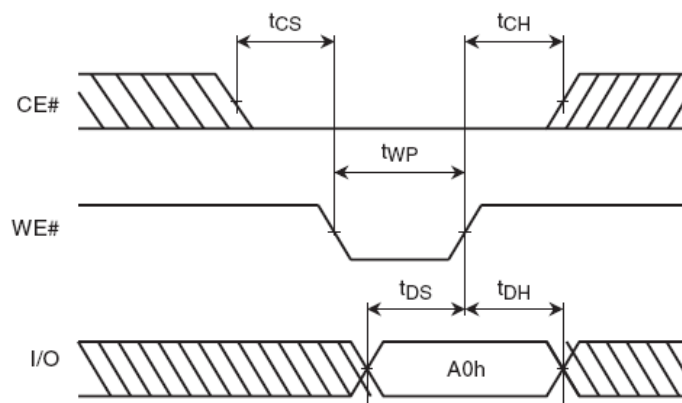
## 4.3 Fundamental NAND Access operations

All of the above operations need to be supported within software and will require additional GPIO management to comply with the /CS, ALE and CLE Timing requirements.

This section looks at the fundamental Read and write timing operations focusing on the EBI read and write cycles comparing these to the NAND requirements.

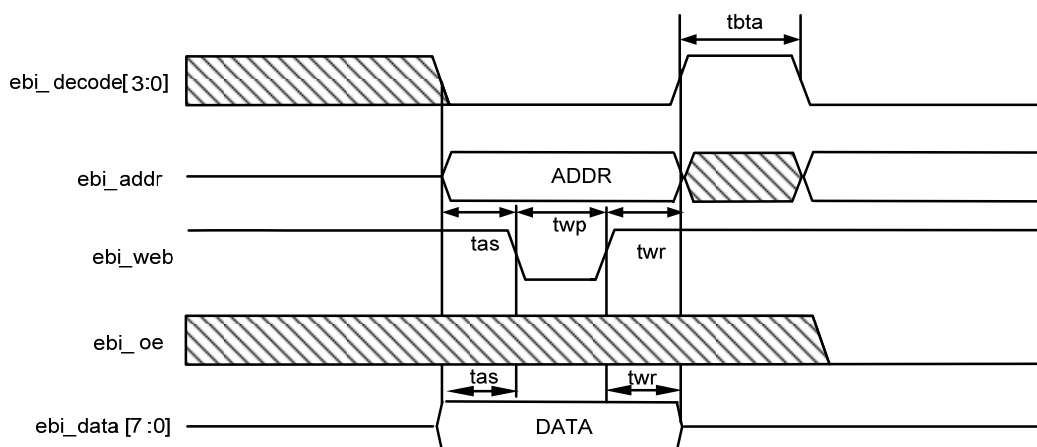
### 4.3.1 NAND single write Access.

**Figure 15: NAND single write Timing Diagram**



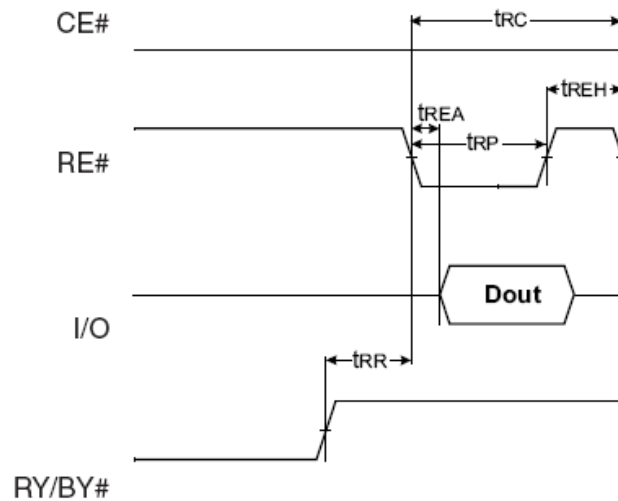
### 4.3.2 EBI Write Operation.

**Figure 16: NAND single write Timing Diagram**



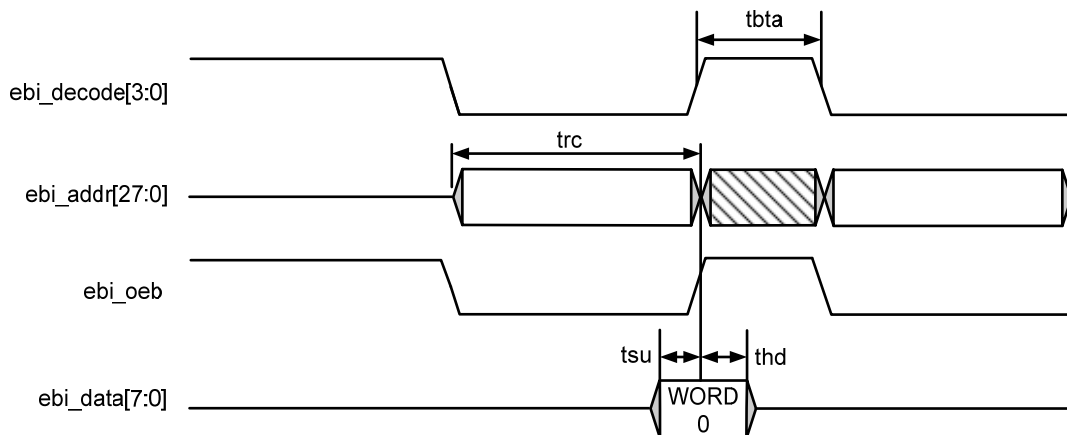
#### 4.3.3 NAND Single Read Operation.

Figure 17: NAND single read Timing Diagram



#### 4.3.4 EBI Read Operation.

Figure 18: EBI Read Operation Timing Diagram



## 4.4 Read and Write Timing parameter comparison

Table 1: NAND AC Characteristics

<i>Spanion S30ML-PNAND Parameter</i>	<i>Symb ol</i>	<i>Min (ns) x8</i>	<i>Max (ns ) x8</i>	<i>Min (ns) x16</i>	<i>Max (ns) x16</i>	<i>EBI Related Parameter</i>
Data Hold Time	t <sub>DH</sub>	5				thd
CE Access Time	t <sub>CEA</sub>		23		35	trc (Read) and tas+twp+twr (write) – Not Compatible Managed by S.W
RE Access Time	t <sub>REA</sub>		18		30	trc
Ready to RE Low	t <sub>RR</sub>	20		20		– Not Compatible Managed by S.W
	t <sub>CLH</sub>	10		10		– Not Compatible Managed by S.W
ALE Hold Time	t <sub>ALH</sub>	10		10		– Not Compatible Managed by S.W
CE Hold Time	t <sub>CH</sub>	10		10		– Not Compatible Managed by S.W
RE High Hold Time	t <sub>REH</sub>	5		15		tbta
WE Pulse Width	t <sub>WP</sub>	15		25		twp
RE Pulse Width	t <sub>RP</sub>	20		30		trc
Write Cycle Time	t <sub>WC</sub>	30		45		tcsu + twp + tas +twr
Read Cycle Time	t <sub>RC</sub>	30		50		tcsu + trc+ + tbta
						tcsu – time for Control (ALE and CLE) and /CS set up time ( GPIO control configurable be software)

### 4.4.1 EBI Timing set Write Access

Table 2: EBI write timing AC characteristics

<i>Parameter</i>	<i>Time(ns)</i>	<i>Value At reset (EBI clks)</i>	<i>NAND Value (EBI clks)</i>	<i>Notes</i>
tbta	35nS	7	TBA	Bus turn around time for read/write or write/read access
twp	50nS	10	TBA	Write pulse length
twr	15nS	3	TBA	Write address/data hold
tas	15nS	3	TBA	Address set up time to write pulse driven low

### 4.4.2 EBI Timing set Read Access

Table 3: EBI read timing AC characteristics

<i>Parameter</i>	<i>Time(ns)</i>	<i>Value At reset (EBI clks)</i>	<i>NAND Value (EBI clks)</i>	<i>Notes</i>
trc	100nS	20	TBA	Read cycle time, address/select to data valid
Tbta	35nS	7	TBA	Bus turn around time for read/write or write/read access.

## 5 GPIO control signal requirements.

### 5.1 /CE ALE and CLE control signals.

To meet the specific timings detailed above as under S.W control GPIO lines are required to assist full NAND support.

**Ready/Busy# (R/B)** - A GPIO line is dedicated to read the Ready/Busy# (R/B) signal provided by the NAND Flash device. This signal is an input GPIO and should be monitored / interrogated prior to any given NAND access.

**Chip Select /CS** – There are two types of flash requirements, some flash devices do not care about the /CS signal during read accesses, other flash devices require that the /CS remains low during all access types and for the entire access period. In the case when interfacing to a Standard NAND Flash, a GPIO line is dedicated to drive the CE signal.

**ALE and CLE Control signals** – Due to the minimum timing requirements of tCLR, tAR and tALH of 10ns the signals ALE and CLE are required to be present prior to a given access type. The following table details the state of the GPIO signals for a given Access type.

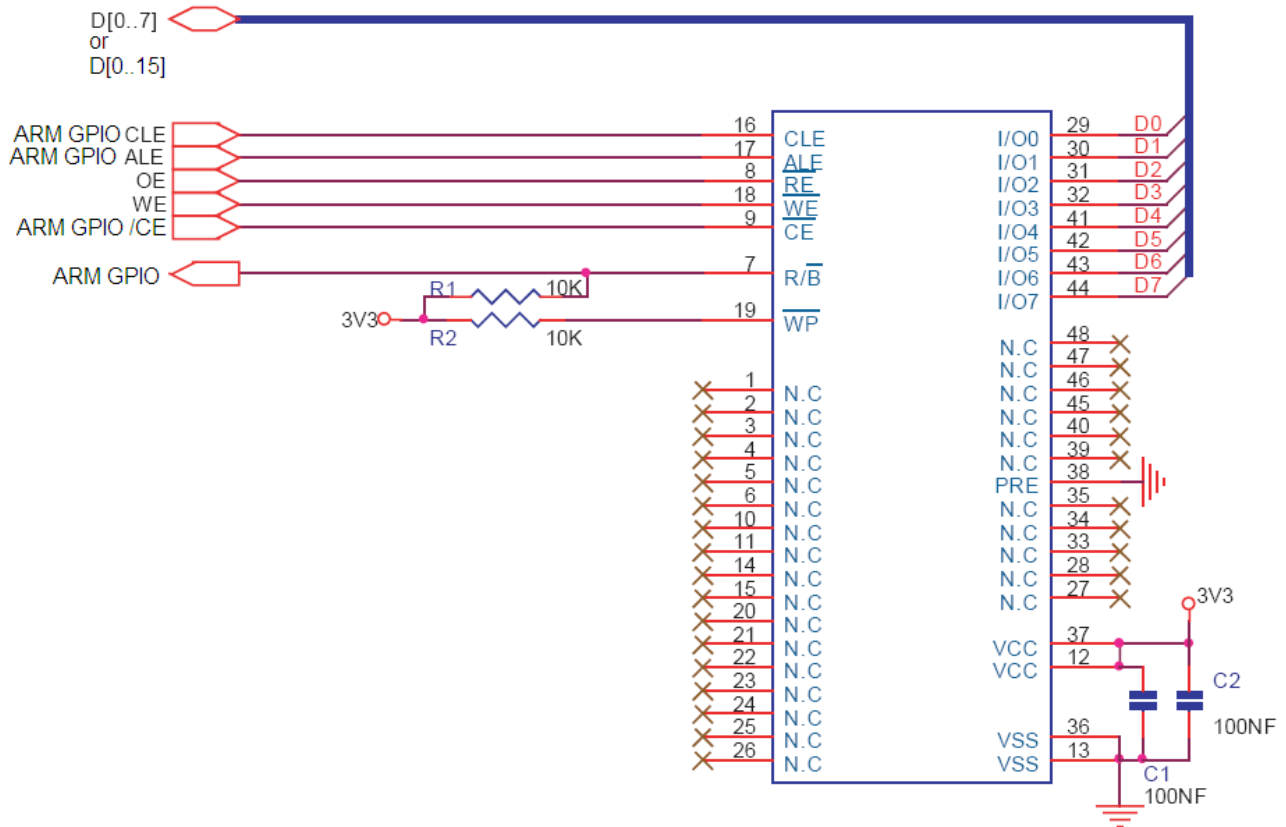
**Table 4: GPIO State Table**

<i>GPIO - CLE</i>	<i>GPIO - ALE</i>	<i>GPIO - /CE</i>	<i>NAND Register Selected</i>
0	0	1	DATA register
0	1	1	ADDRESS register
1	0	1	COMMAND register



## 6 Hardware connectivity

Figure 19: x8 and x16 EBI to NAND connections



### 6.1 Software configuration

The following configuration must be carried out:

- Configure a GPIO line as an input and enable the clock of this GPIO to manage the Ready/Busy signal.
- Configure a GPIO line as an output and enable the clock of this GPIO to manage the ALE signal.
- Configure a GPIO line as an output and enable the clock of this GPIO to manage the CLE signal
- Configure a GPIO line as an output and enable the clock of this GPIO to manage the /CS. For /CS do not care devices this GPIO signal is not required Check the NAND datasheet to see if your device has the full /CS requirements.
- Configure the Static Memory Timing Register - Set 1 (SMTMGR\_SET1) depending on NAND Flash device timings.
- Control GPIO signals as per Table 4: GPIO State Table

**Table 5: NAND pin description**

Pin	Description
I/O7 I/O0	– Data Inputs/Outputs. The I/O0 to I/O7 pins are used for transferring address, command, and input data to the device and output data from the device. Active for x8 and x16 ORNAND device configurations.
I/O15 I/O8	– Data Inputs/Data Outputs. The I/O8 to I/O15 pins are used for transferring address, command, and input data to the device and output data from the device. Active only for x16 ORNAND device configuration. I/O8 to I/O15 must be low level during address and command input.
CLE	Command Latch Enable. The CLE input signal is used to control the loading of any command into the internal command register. The command is always latched into the internal command register from the data inputs on the rising edge of WE# signal while the CLE signal is active high.
ALE	Address Latch Enable. The ALE input signal is used to control the loading of any address into the internal address register. The address is always latched into the internal address register from the data inputs on the rising edge of WE# signal while the ALE signal is active high.
CE#	Chip Enable. The CE# input signal controls if the device is selected. When the device is in the Busy State (RY/BY# = L) while a read, program, or erase operation is in progress, the CE# signal going high is ignored. While in Busy State, the device will not enter Standby Mode even with the CE# signal going high.
RE#	Read Enable. The RE# input signal controls reads from the device. Output data is driven and becomes available tREA time after the falling edge of RE# signal. The internal address column counter increments up one address every RE# rising edge.
WE#	Write Enable. The WE# input signal controls writes to the device. Commands, addresses, and input data are latched on the rising edge of WE# signal.
WP#	Write Protect. The WP# input signal is used to protect the device from accidental programming or erasing. When WP# signal is asserted low, the entire memory is protected from writes and no program and erase operation can execute.
PRE	Power-On Read Enable. The PRE input signal controls the automatic read operation execution during power-on. The power-on automatic read feature is enabled when PRE signal is asserted high during power-on and allows page 0 to be automatically read out of the device so any system can automatically shadow boot code into DRAM without having to issue a read command. It is recommended that the user tie the PRE input pin to VCC.
RY/BY#	Ready/Busy. The RY/BY# output signal is used to indicate the operating condition of the device. The RY/BY# signal is always in the Busy State and asserts low when the device is executing read, program, and erase operations. When a read, program, or erase operation has completed, the RY/BY# signal stops asserting low to indicate completion and that the device is ready for a new operation. Since the RY/BY# output is open-drain, an external pull-up resistor is required.
VCC	Power Supply. The VCC input is the main power supply for this device.
VSS	Ground. The VSS input is the main supply ground for this device.
NC	No Connect. Lead is not internally connected.
VIO	VIO is the I/O power supply for device. The VIO pin exists only if the Enhanced Versatile I/O control feature is needed through a different product ordering part number.
FP#	Fast Program/Erase Mode. FP# is used to set the device in standard mode or Fast Program/Erase Mode. When FP# is held at VIL, the device operates in Fast Program/Erase Mode. When FP# is held at VIH, the device operates in standard mode. Note: FP# contains an internal pull-up. When unconnected, FP# is at VIH.

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## 8 Version History

Version	Date	Author(s)	Changes made
1.0	5 <sup>th</sup> Dec	RR	Initial release for review

## 9 Appendix A NAND AC Characteristics.

Parameter	Description	Min. (x8, no V <sub>IO</sub> )	Max (x8, no V <sub>IO</sub> )	Min. (x8 with V <sub>IO</sub> , x16 no V <sub>IO</sub> , x16 with V <sub>IO</sub> )	Max (x8 with V <sub>IO</sub> , x16 no V <sub>IO</sub> , x16 with V <sub>IO</sub> )	Unit
t <sub>CLS</sub>	CLE Setup Time	0	-	0	-	ns
t <sub>CLH</sub>	CLE Hold Time	10	-	10	-	
t <sub>CS</sub>	CE Setup Time	0	-	0	-	
t <sub>CH</sub>	CE Hold Time	10	-	10	-	
t <sub>WP</sub>	Write Pulse Width (See Note)	15	-	25	-	
t <sub>ALS</sub>	ALE Setup Time	0	-	0	-	
t <sub>ALH</sub>	ALE Hold Time	10	-	10	-	
t <sub>DS</sub>	Data Setup Time	15	-	20	-	
t <sub>DH</sub>	Data Hold Time	5	-	10	-	
t <sub>WC</sub>	Write Cycle Time	30	-	45	-	
t <sub>WH</sub>	WE# High Hold Time	10	-	15	-	
t <sub>WW</sub>	WP# High to WE# Low	100	-	100	-	
t <sub>RR</sub>	Ready to RE# Falling Edge	20	-	20	-	
t <sub>RW</sub>	Ready to WE# Falling Edge	20	-	20	-	
t <sub>RP</sub>	Read Pulse Width	20	-	30	-	
t <sub>RC</sub>	Read Cycle Time	30	-	50	-	
t <sub>REA</sub>	RE# Access Time	-	18	-	30	
t <sub>CEA</sub>	CE# Access Time	-	23	-	35	
t <sub>CLR</sub>	CLE to RE# delay	10	-	10	-	
t <sub>ALEA</sub>	ALE Access Time	-	28	-	40	
t <sub>OH</sub>	Data Output Hold Time	10	-	10	-	
t <sub>RHZ</sub>	RE# High to Output High Impedance	-	40	-	40	
t <sub>CHZ</sub>	CE# High to Output High Impedance	-	40	-	40	
t <sub>REH</sub>	RE# High Hold Time	5	-	15	-	
t <sub>IR</sub>	Output High Impedance to RE# Falling Edge	0	-	0	-	
t <sub>RHW</sub>	RE# High to WE# Low	30	-	30	-	
t <sub>WHC</sub>	WE# High to CE# Low	30	-	30	-	
t <sub>WHR</sub>	WE# High to RE# Low	60	-	60	-	
t <sub>R</sub>	Data Transfer from Memory to Register	-	9	-	9	μs
t <sub>WB</sub>	WE# High to Busy	-	100	-	100	ns
t <sub>RST</sub>	Device Reset (Read/Program/Erase)	Read	5	-	5	μs
		Program	10	-	10	
		Erase	500	-	500	
t <sub>READ</sub>	RE# Access Time (Read ID)		18	-	18	ns

## 10 Appendix B – ECC.C code example

```

/*****
*
*   File Name:   ECC.c
*   Revision:    1.0
*   Date:        Jan 20, 2006
*   Email:        nandsupport@micron.com
*   Company:     Micron Technology, Inc.
*
*   Description:  Micron NAND I/O Driver
**
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*
*   Rev   Author           Date           Changes
*   ---   -
*   1.0   WW               01/20/2006   Initial release
*/

#include <Windows.h>
#include <assert.h>

typedef unsigned short  u16;
typedef unsigned char*  u8p;
typedef unsigned short* u16p;
typedef unsigned*       u32p;
typedef void *          voidp;

```

## PC20x and PC302 NAND Interfacing App note.

# APP-42

```
typedef signed char s8;
typedef unsigned char u8;

typedef signed short s16;
typedef unsigned short u16;

typedef signed int s32;
typedef unsigned int u32;
```

```
u8 gSilent = 1;
```

```
/*
```

```
[Data Format]
```

```
-----
7           6           5           4           3           2           1
0
```

```
...
Byte0 P8e | P16e | P32e | P2048e
...
Byte1 P8o |      |      |
...
Byte2 P8e | P16o |      |
...
Byte3 P8o |      |      |
...
```

```
...
| P2048o
```

```
...
Byte512 P8o |
```

```
-----
P1o      P1e      P1o      P1e      p1o      P1e
P1o      P1e
```

```
-----
P2o      P2e      ....
-----
P4o      P4e
```

```
[Reg Format]
```

```
-----
31 ... 27      26      .... 16      15      14      .... 2      1      0
```

```
-----
P2048O P1024O      P1O      P2048E P1024E      P4E P2E P1E ?
```

```
EO or OE
```

```
[Calc Format]
```

```
-----
7           6           5           4           3           2           1
0
```

```
-----
P128e P64e P32e P16e P8e P4e P2e P1e
-----
```



## PC20x and PC302 NAND Interfacing App note.

# APP-42

```
P128o ..... P10
-----
P2048o P1024o P512o P256o P2048e P1024e P512e P256e
-----

[Fail Bit Address Offset]
-----
<P2048 P1024 ... P4 P2 P1> ==> 11 bit
-----
-----
-----
-----
```

\*/

```
#define P1EMask      (1 << 0)
#define P2EMask      (1 << 1)
#define P4EMask      (1 << 2)
#define P8EMask      (1 << 3)
#define P16EMask     (1 << 4)
#define P32EMask     (1 << 5)
#define P64EMask     (1 << 6)
#define P128EMask    (1 << 7)
#define P256EMask    (1 << 8)
#define P512EMask    (1 << 9)
#define P1024EMask   (1 << 10)
#define P2048EMask   (1 << 11)

#define P1OMsk       (1 << 16)
#define P2OMsk       (1 << 17)
#define P4OMsk       (1 << 18)
#define P8OMsk       (1 << 19)
#define P16OMsk      (1 << 20)
#define P32OMsk      (1 << 21)
#define P64OMsk      (1 << 22)
#define P128OMsk     (1 << 23)
#define P256OMsk     (1 << 24)
#define P512OMsk     (1 << 25)
#define P1024OMsk    (1 << 26)
#define P2048OMsk    (1 << 27)

#define TF(value) (value ? 1 : 0)

#define P2048e(a) (TF(a & P2048EMask) << 0 )
#define P2048o(a) (TF(a & P2048OMsk) << 1 )
#define Ple(a)    (TF(a & P1EMask) << 2 )
#define Plo(a)    (TF(a & P1OMsk) << 3 )
#define P2e(a)    (TF(a & P2EMask) << 4 )
#define P2o(a)    (TF(a & P2OMsk) << 5 )
#define P4e(a)    (TF(a & P4EMask) << 6 )
#define P4o(a)    (TF(a & P4OMsk) << 7 )

#define P8e(a)    (TF(a & P8EMask) << 0 )
#define P8o(a)    (TF(a & P8OMsk) << 1 )
```

## PC20x and PC302 NAND Interfacing App note.

# APP-42

```
#define P16e(a)      (TF(a & P16EMask) << 2 )
#define P16o(a)      (TF(a & P16OMsk)  << 3 )
#define P32e(a)      (TF(a & P32EMask) << 4 )
#define P32o(a)      (TF(a & P32OMsk)  << 5 )
#define P64e(a)      (TF(a & P64EMask) << 6 )
#define P64o(a)      (TF(a & P64OMsk)  << 7 )

#define P128e(a)     (TF(a & P128EMask)    << 0 )
#define P128o(a)     (TF(a & P128OMsk) << 1 )
#define P256e(a)     (TF(a & P256EMask)    << 2 )
#define P256o(a)     (TF(a & P256OMsk) << 3 )
#define P512e(a)     (TF(a & P512EMask)    << 4 )
#define P512o(a)     (TF(a & P512OMsk) << 5 )
#define P1024e(a)    (TF(a & P1024EMask)   << 6 )
#define P1024o(a)    (TF(a & P1024OMsk)   << 7 )

#define P8e_s(a)     (TF(a & P8EMask)   << 0 )
#define P8o_s(a)     (TF(a & P8OMsk)    << 1 )
#define P16e_s(a)    (TF(a & P16EMask)  << 2 )
#define P16o_s(a)    (TF(a & P16OMsk)   << 3 )
#define P1e_s(a)     (TF(a & P1EMask)   << 4 )
#define P1o_s(a)     (TF(a & P1OMsk)    << 5 )
#define P2e_s(a)     (TF(a & P2EMask)   << 6 )
#define P2o_s(a)     (TF(a & P2OMsk)    << 7 )

#define P4e_s(a)     (TF(a & P4EMask)   << 0 )
#define P4o_s(a)     (TF(a & P4OMsk)    << 1 )

u8 mu_pack_ecc(u8 id, u8 *ecc_buf)
{
    u32 l;
    l = 0; //mu_ecc_pgseq_val(id);
    ecc_buf[0] = l; // P128e, ..., Ple
    ecc_buf[1] = l >> 16; // P128o, ..., P1o
    ecc_buf[2] = ((l >> 8) & 0x0f) | ((l >> 20) & 0xf0); // P2048o, P1024o,
    P512o, P256o, P2048e, P1024e, P512e, P256e
    printf(" [packecc(%8x -> %3X %3X %3X)]\n", l, ecc_buf[0], ecc_buf[1],
    ecc_buf[2]);
    return 0;
}

u8 mu_count_bits(u32 v)
{
    u8 i, count;

    for(count=i=0; i<32; i++)
        count += (v>>i)&1 ? 1:0;
    return count;
}

u8 mu_unpack_ecc(u8 id, u8 *ecc_mem, u8* ecc_reg, u32* m, u32* r)
{
    u32 mem, reg;

    //reg = mu_ecc_pgseq_val(id);
    mem = ecc_mem[0] | (ecc_mem[1] << 16) | ((ecc_mem[2] & 0xf0) << 20) |
```

## PC20x and PC302 NAND Interfacing App note.

# APP-42

```
((ecc_mem[2] & 0x0F) << 8);
    reg = ecc_reg[0] | (ecc_reg[1] << 16) | ((ecc_reg[2] & 0xF0) << 20) |
    ((ecc_reg[2] & 0x0F) << 8);
    if(!gSilent) printf("[unpacked(%3X %3X %3X) (mem:reg=%8x:%8x) ",
ecc_mem[0], ecc_mem[1], ecc_mem[2], mem, reg);
    if( mem == reg )
    {
        if(!gSilent) printf("\n");
        return 0;
    }
    else
    {
        u32 tmp;
        tmp = mem ^ reg;
        if(!gSilent) printf("mu_unpack_ecc: XOR=%x XorBits=%X Xor&memBits=%x
Xor&regBits=%x\n",
            tmp, mu_count_bits(tmp), mu_count_bits(tmp&mem),
mu_count_bits(tmp&reg) );
        *m = mem;
        *r = reg;
    }

    return 1;
}

u8 mu_ecc_correct(u32 m, u32 r, u8 *buf)
{
    u16 pe, po, is_ecc_ff;

    is_ecc_ff = ((m & 0xFFFFFFFF) == 0xFFFFFFFF);
    m = m^r;

    switch (mu_count_bits(m))
    {
        case 0: // shall never get there since ecc equal, no call in
            return 0;
        case 1: // dont correct
            if(!gSilent) printf ( "ECC area error. No need to
correct.\n");
            return 0;
        case 12: // Correctable ?
            po = m & 0x0000FFFF;
            pe = (m>>16) & 0x0000FFFF;
            po = (pe^po);
            if( 0x0FFF == po )
            {
                buf[pe>>3] ^= (1 << (pe&7));
                if(!gSilent) printf ( "Single bit error: offset: %d,
bit: %d\n", pe>>3, pe&7);
                return 0;
            }
            else
            {
                if(!gSilent) printf( "Uncorrectable error A !! \n");
                return -1;
            }
    }
}
```

```

        default:
            if(is_ecc_ff && r == 0)
                return 0;
            if(!gSilent) printf( "Uncorrectable error B !! \n");
            return -1;
    }
}

u8 mu_ecc_generate_512(u8 *eccbuf, u8 *datbuf)
{
    u32 i, j;
    u8   byteParity[512], tmp = 0, tmp2=0;
    u8   parity_LUT[32] = {0,1,1,0,1,0,0,1,1,0,0,1,0,1,1,0, /**/
1,0,0,1,0,1,1,0,0,1,1,0,1,0,0,1};
    u8   sum=0, Pcount = 0;
    u8   Pc0 = 0, Pc1 = 0, Pc2 = 0, Pc3 = 0, Pc4 = 0, Pc5 = 0, Pc6 = 0, Pc7 =
0;
    u8   PE1, PO1, PE2, PO2, PE4, PO4;
    u8   PE8 = 0, PO8 = 0, PE16 = 0, PO16 = 0, PE32 = 0, PO32 = 0;
    u8   PE64 = 0, PO64 = 0, PE128 = 0, PO128 = 0, PE256 = 0, PO256 = 0;
    u8   PE512 = 0, PO512 = 0, PE1024 = 0, PO1024 = 0, PE2048 = 0, PO2048 =
0;

    for( i = 0; i < 512; i++)
    {
        Pcount = Pcount ^ datbuf[i];
        tmp = (datbuf[i] & 0xf0) >> 4;
        tmp2 = datbuf[i] & 0x0f;
        switch(tmp)
        {
            case 0:      case 3:      case 5:      case 6:      case 9:
case 10: case 12: case 15:
                byteParity[i] = parity_LUT[tmp2]; break;
            default:
                byteParity[i] = parity_LUT[tmp2+16]; break;
        }
    }

    Pc0 = ((Pcount & 0x01) ? 1 : 0);
    Pc1 = ((Pcount & 0x02) ? 1 : 0);
    Pc2 = ((Pcount & 0x04) ? 1 : 0);
    Pc3 = ((Pcount & 0x08) ? 1 : 0);
    Pc4 = ((Pcount & 0x10) ? 1 : 0);
    Pc5 = ((Pcount & 0x20) ? 1 : 0);
    Pc6 = ((Pcount & 0x40) ? 1 : 0);
    Pc7 = ((Pcount & 0x80) ? 1 : 0);

    PO1 = Pc6 ^ Pc4 ^ Pc2 ^ Pc0;
    PE1 = Pc7 ^ Pc5 ^ Pc3 ^ Pc1;
    PO2 = Pc5 ^ Pc4 ^ Pc1 ^ Pc0;
    PE2 = Pc7 ^ Pc6 ^ Pc3 ^ Pc2;
    PO4 = Pc3 ^ Pc2 ^ Pc1 ^ Pc0;
    PE4 = Pc7 ^ Pc6 ^ Pc5 ^ Pc4;

    for( i = 0 ; i < 512;i++)
        sum=sum ^ byteParity[i];

```

```
for ( i = 0; i < 512; i = i+2 )
    PO8 = PO8 ^ byteParity[i];

for ( i = 0; i < 512; i = i+4 )
    {
        PO16 = PO16 ^ byteParity[i];
        PO16 = PO16 ^ byteParity[i + 1];
    }

for ( i = 0; i < 512; i = i+8 )
    {
        for ( j = 0; j <= 3; j++ )
            PO32 = PO32 ^ byteParity[i+j];
    }

for ( i = 0; i < 512; i = i+16 )
    {
        for ( j = 0; j <= 7; j++ )
            PO64 = PO64 ^ byteParity[i+j];
    }

for ( i = 0; i < 512; i = i+32 )
    {
        for ( j = 0; j <= 15; j++ )
            PO128 = PO128 ^ byteParity[i+j];
    }

for ( i = 0; i < 512; i = i+64 )
    {
        for ( j = 0; j <= 31; j++ )
            PO256 = PO256 ^ byteParity[i+j];
    }

for ( i = 0; i < 512; i = i+128 )
    {
        for ( j = 0; j <= 63; j++ )
            PO512 = PO512 ^ byteParity[i+j];
    }

for ( i = 0; i < 512; i = i+256 )
    {
        for ( j = 0; j <= 127; j++ )
            PO1024 = PO1024 ^ byteParity[i+j];
    }

for ( i = 0; i < 512; i = i+512 )
    {
        for ( j = 0; j <= 255; j++ )
            PO2048 = PO2048 ^ byteParity[i+j];
    }

if(sum==0)
    {
        PE2048=PO2048;
        PE1024=PO1024;
        PE512=PO512;
        PE256=PO256;
        PE128=PO128;
        PE64=PO64;
        PE32=PO32;
        PE16=PO16;
```

PC20x and PC302 NAND Interfacing App note.

# APP-42

```

        PE8=PO8;
    }
else
{
    PE2048 = (PO2048 ? 0 : 1);
    PE1024 = (PO1024 ? 0 : 1);
    PE512  = (PO512  ? 0 : 1);
    PE256  = (PO256  ? 0 : 1);
    PE128  = (PO128  ? 0 : 1);
    PE64   = (PO64   ? 0 : 1);
    PE32   = (PO32   ? 0 : 1);
    PE16   = (PO16   ? 0 : 1);
    PE8    = (PO8    ? 0 : 1);
}

eccbuf[0]=(PO128 << 7) |(PO64 << 6) |(PO32 << 5) |(PO16 << 4) |(PO8 << 3)
|(PO4 << 2) |(PO2 << 1) |(PO1);
eccbuf[1]=(PE128 << 7) |(PE64 << 6) |(PE32 << 5) |(PE16 << 4) |(PE8 << 3)
|(PE4 << 2) |(PE2 << 1) |(PE1);
eccbuf[2]=(PE2048 << 7) |(PE1024 << 6) |(PE512 << 5) |(PE256 << 4)
|(PO2048 << 3) |(PO1024 << 2) |(PO512 << 1) |(PO256);

if(0)
{
    u8    ecctmp[3];
    u32 tmp = eccbuf[0] |(eccbuf[1] << 16) | ((eccbuf[2] & 0xF0) << 20)
| ((eccbuf[2] & 0x0F) << 8);

    ecctmp[0] = ~(P64o(tmp) | P64e(tmp) | P32o(tmp) | P32e(tmp) |
P16o(tmp) | P16e(tmp) | P8o(tmp) | P8e(tmp) );
    ecctmp[1] = ~(P1024o(tmp) | P1024e(tmp) | P512o(tmp) | P512e(tmp) |
P256o(tmp) | P256e(tmp) | P128o(tmp) | P128e(tmp));
    ecctmp[2] = ~( P4o(tmp) | P4e(tmp) | P2o(tmp) | P2e(tmp) | P1o(tmp)
| P1e(tmp) | P2048o(tmp) | P2048e(tmp));

    printf("mu_prt_ecc: %3X %3X %3X \n", ecctmp[0], ecctmp[1],
ecctmp[2]);

    printf("    P2048o.e(tmp)      = %d : %d\n", P2048o(tmp)?1:0,
P2048e(tmp)?1:0);
    printf("    P1024o.e(tmp)      = %d : %d\n", P1024o(tmp)?1:0,
P1024e(tmp)?1:0);
    printf("    P512o.e(tmp)       = %d : %d\n", P512o(tmp)?1:0,
P512e(tmp)?1:0);
    printf("    P256o.e(tmp)       = %d : %d\n", P256o(tmp)?1:0,
P256e(tmp)?1:0);
    printf("    P128o.e(tmp)       = %d : %d\n", P128o(tmp)?1:0,
P128e(tmp)?1:0);
    printf("    P64o.e(tmp) = %d : %d\n", P64o(tmp)?1:0, P64e(tmp)?1:0);
    printf("    P32o.e(tmp) = %d : %d\n", P32o(tmp)?1:0, P32e(tmp)?1:0);
    printf("    P16o.e(tmp) = %d : %d\n", P16o(tmp)?1:0, P16e(tmp)?1:0);
    printf("    P8o.e(tmp)  = %d : %d\n", P8o(tmp)?1:0, P8e(tmp)?1:0);
    printf("    P4o.e(tmp)  = %d : %d\n", P4o(tmp)?1:0, P4e(tmp)?1:0);
    printf("    P2o.e(tmp)  = %d : %d\n", P2o(tmp)?1:0, P2e(tmp)?1:0);
    printf("    P1o.e(tmp)  = %d : %d\n", P1o(tmp)?1:0, P1e(tmp)?1:0);
}

```

## PC20x and PC302 NAND Interfacing App note.

# APP-42

```

    return 0;
}

// Unit testing

#if 1

void HammingInstErrSimple(u8*      buf, u16 len)
{
    u16      j, err;
    u8       mask, bf, af;
    #define MaxErr 1

    for(err=0; err<MaxErr; )
    {
        j = rand()%len;
        assert(j<len);
        mask = ~( 1<<(rand()%8) );
        if( (buf[j] & mask) != buf[j] )
        {
            bf = buf[j];
            buf[j] &= mask;
            af = buf[j];
            printf("%d %X %X\n", j, bf, af);
            err++;
        }
    }
}

extern u8 tstdat[2112];

int main(int argc, char* argv[])
{
    int i, nNG=0, nOK=0;
    u32 m,r;

    u8 eccbuf[4], eccbuf2[4];

    mu_ecc_generate_512(eccbuf, tstdat);
    printf("eccbuf: %2X %2X %2X \n", eccbuf[0], eccbuf[1], eccbuf[2]);
    mu_ecc_generate_512(eccbuf, tstdat+512);
    printf("eccbuf: %2X %2X %2X \n", eccbuf[0], eccbuf[1], eccbuf[2]);
    mu_ecc_generate_512(eccbuf, tstdat+1024);
    printf("eccbuf: %2X %2X %2X \n", eccbuf[0], eccbuf[1], eccbuf[2]);
    mu_ecc_generate_512(eccbuf, tstdat+1024+512);
    printf("eccbuf: %2X %2X %2X \n", eccbuf[0], eccbuf[1], eccbuf[2]);

    nNG=nOK=0;
    for(i=0; i<800; i++)
    {
        printf("[%d] \n", i);
        mu_ecc_generate_512(tstdat+512, tstdat);
        if(i<400)
            HammingInstErrSimple(tstdat, 512);
    }
}

```

```

else
    HammingInstErrSimple(tstdat+512, 3);
    mu_ecc_generate_512(eccbuf, tstdat);
    printf("ecc: Before=%2X %2X %2X : After=%2X %2X %2X \n",
tstdat[512+0], tstdat[512+1], tstdat[512+2], eccbuf[0], eccbuf[1], eccbuf[2]);
    if( mu_unpack_ecc(0, tstdat+512, eccbuf, &m, &r) )
    {
        if( mu_ecc_correct(m, r, tstdat) )
        {
            nNG++;
        }
        else
        {
            nOK++;
        }
    }
    else
    {
        printf("
error detected!\n");
        while(1);
    }
    }
    printf("
%d\n", nNG, nOK);
}

#endif

```

No

NG OK = %d